



It would be a good idea to have someone read through the application documents before filing, as soon as possible, since the specification currently contains several incomplete sentences; this does not contribute to the required clarity. Patent claims should be formulated in the two-part form which was proven as early as the 19th century, as is explained and substantiated in the instructions for an applicant or also in the 4th and 5th paragraph in the attached form PA 3. In this way it is more clearly obvious what can be considered known and what the invention is actually supposed to represent. A list of patent attorneys with extensive experience in the formulation of such claims is attached.

The filed application cannot be granted since it does not meet the requirements of Section 91 of the Patent Law for accurate, complete and distinguishing characterization. Many of the claims (for example, 1, 8, 9, 10, 14) contain simply wishes, without specifically indicating how they are to be fulfilled. The completely general "wafer-shaped article" should be characterized so precisely in claim 1 that it clearly follows that it is not a beverage coaster, such as for example a beer mat. Furthermore, it should be specified there that the "defined section" is a circular ring (near the edge) which runs from the edge to the inside. The required complete characterization of the device in the application includes the measures cited in current claims 3, 8 and 11 incorporated into the main claim. Moreover, it should

be stated there that a wafer carrier, a mask carrier and the possibility of feeding treatment liquid must necessarily be present. Furthermore, figure references should be added to the application for purposes of greater clarity.

For the prior art, the specification names JP 9181026 A in which the circular ring-shaped part placed near the suction nozzle 16 in Figure 3 can be regarded as a mask, and US 4 838 289 A in which the cylinder (tops) 14, 18 and 165, 162 (Figures 1 and 9) which are located a short distance from the wafer can likewise be regarded as a circular ring-shaped mask.

EP 1 020 894 A of the applicant points out in sections 5 and 8 the possibility of the treatment medium via the wafer edge reaching the bottom of the wafer and gives preventative measures. As claimed in claim 6 of EP 810 614 A2 (Siemens, 7 pages) the etching agent can also be an etching solution. Then the outside diaphragms 20, 21 with their short distances from the wafer also act as annular masks. The upper end 42a of the guide plate 42 in Figure 7 of US 5 608 943 A (KONISHI, 22 pages) can also be regarded as a mask. Finally, in the last paragraph of EP 844 646 A2 of the applicant measures are given for wetting the bottom along the peripheral edge of semiconductor wafers.

The applicant is invited to describe to what extent the device in the application does not follow from the indicated prior art in an obvious manner.

In the case in which this application is pursued, a new application which has been accurately formulated in a distinguishing manner should be delineated from the prior art and

the specification matched to its wording. The specification is filed at the same time for making corrections.

In the drawings, in Figure 2, item 13, in Figure 3 items 23, 24, and 26, in Figure 4 item 14 and Wb and in Figure 5 the axis A and the broken line should be added.